

INTERNATIONAL CONFERENCE ON 3D IMMERSION 2020 CALL FOR PAPERS

15 DECEMBER 2020
BRUSSELS, BELGIUM

IC3D will be held either *in-person* at The Egg Brussels, located in the heart of the Capital of Belgium and the European Union; or *virtually*. In the title of the conference, “immersion”, possibly qualified by “3D”, refers to the creation of depth and volume, in images and sound, with appropriate input and output means, for virtual reality (VR), augmented reality (AR), mixed reality (MR) and extended reality (XR). The conference covers, among others, the creation and capture of immersive content, novel 3D rendering techniques for ultra-realistic content (including holography) and/or real-time rendering, as well as multi-cameras’ light field compression.

Scope

IC3D has for scope ALL aspects – scientific, engineering, physical, mathematical, algorithmic, ... - and ALL applications of ALL forms of 3D immersion, with emphasis on 3D imaging and 3D sound. The scope includes all possible signal processing in each conceivable, end-to-end 3D processing chain, e.g., capture of real 3D images and sound, their synthetic generation, pre-processing and scene modelling, as well as coding, transmission, storage, and post-processing for visualization, sound spatialization and other forms of exploitation. IC3D also explores the many applications of 3D immersion, including in industry, engineering, R&D, design, maintenance, science, medicine, psychology, architecture, real estate, defence, communication, advertisement, culture, education, and entertainment.

These aspects will be covered over four thematic sessions:

- Capture and creation of immersive VR/AR/MR/XR content
- Light field coding, mesh and point cloud coding, and transmission
- Real-time 3D rendering techniques
- Ultra-realistic rendering, including holography

Context and activities

While IC3D is a self-contained event, it is nevertheless seamlessly integrated into Stereopsia, the World Immersion Forum. This umbrella event includes several components, including IC3D, thematic conferences, an exhibition and an Awards dinner. Stereopsia will take place at The Egg Brussels on 14-16 Dec 2020; information can be found at www.stereopsia.com.

As for all preceding editions, IC3D is expected to be technically co-sponsored by the **IEEE Signal Processing Society**, and its proceedings to be archived in the IEEE Xplore Digital Library. The Best Paper Award will be in the form of a prestigious Lumiere Award from The Advanced Imaging Society from Hollywood, also won in the US by world-renowned 3D cinematographers James Cameron, Ang Lee, Martin Scorsese, and Steven Spielberg, among others. The annual meeting of the H2020 XR4ALL project will take place jointly with Stereopsia.



Key events and dates

Issuance of the Call for papers: 8 June 2020

Deadline for submitting papers: ~~10 September 2020~~ - 30 October 2020 (*this deadline is rather flexible*)

Notification of acceptance/rejection: ~~1 October 2020~~ - 15 November 2020

Deadline for submitting camera-ready papers: ~~15 November 2020~~ - 1 December 2020

IC3D conference: 15 December 2020

Submission link

<http://openconf.stereopsia.com/openconf.php>

Technical program committee

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